

GENERAL DESCRIPTION

All devices utilize the most advanced design and process technologies. These features provide the most consistent and reliable chip and package combination designed, built and tested specifically for use in airborne DME.

- * Gold thin-film metallization -- proven highest Mean Time to Failure.
- * Surface passivation -- eliminates contamination and extends life.
- * Eutectic die attach -- reduces junction temperature and extends MTTF.
- * Gold controlled-loop wire bonding -- consistent RF performance.
- * Low thermal-resistance packages -- reduce junction temperature and extend life.

ABSOLUTE MAXIMUM RATINGS

Maximum Power Dissipation @ 25 °C Case Temperature 290 W

Maximum Voltage and Current

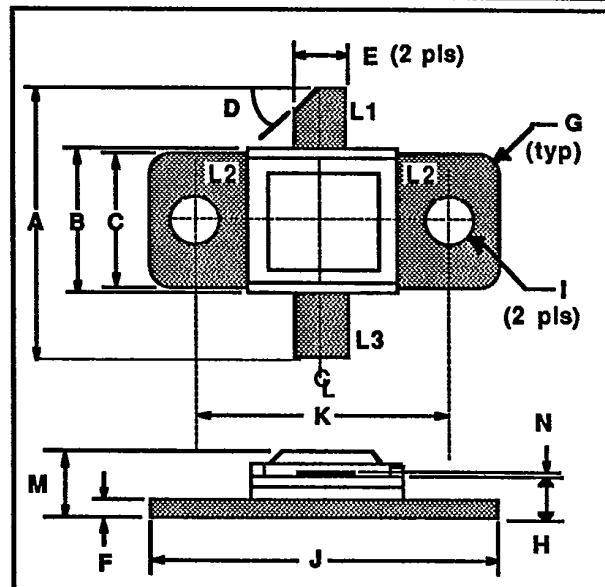
BVces Collector to Emitter Voltage 55 V
 BVebo Emitter to Base Voltage 4.0 V
 Ic Collector Current 0.15 A

Maximum Temperatures

Storage Temperature -65 to +150 °C
 Operating Junction Temperature +200 °C

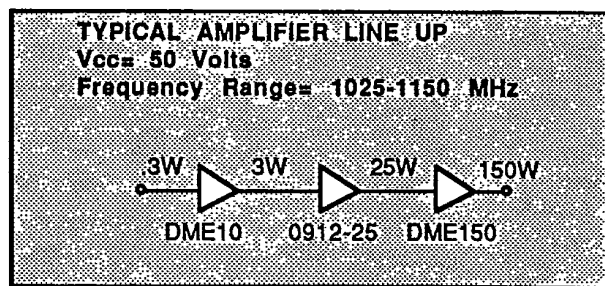
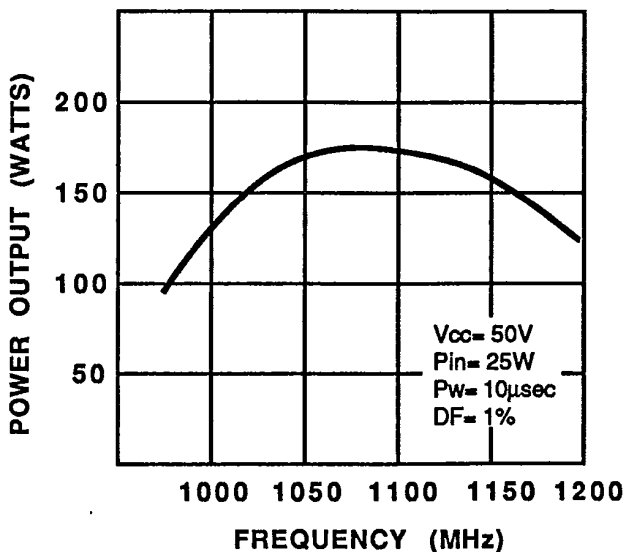
DME 150
 150 WATTS - 50 VOLTS
 1025/1150 MHz

AVIONICS



DIM	Millimeter	TOL	Inches	TOL
L1 : c				
L2 : b				
L3 : e				
A	20.32	.76	.800	.030
B	10.16	.13	.400	.005
C	9.78	.13	.385	.005
D	45 °	5 °	45 °	5 °
E	3.81	.13	.150	.005
F	1.52	.13	.060	.005
G	1.52 R	.13	.060 R	.005
H	3.05	.13	.120	.005
I	3.30 DIA	.13	.130 DIA	.005
J	22.86	.13	.900	.005
K	16.51	.13	.650	.005
M	4.70	REF	.185	REF
N	0.13	.02	.005	.001

(TYPICAL) POWER OUTPUT



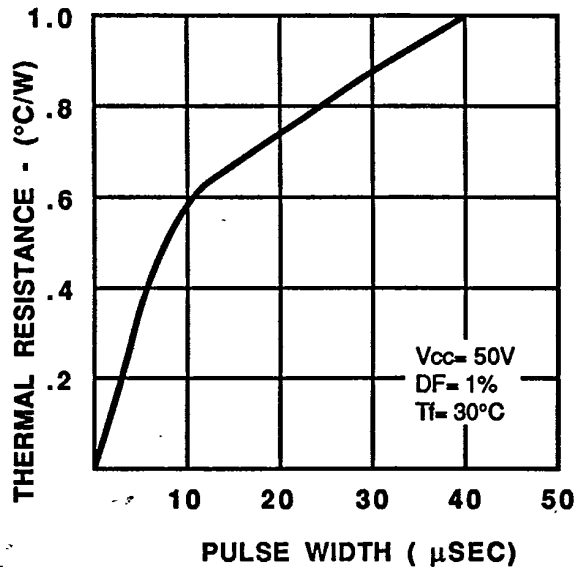
DME 150-2

ELECTRICAL CHARACTERISTICS¹

SYMBOL	CHARACTERISTICS	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
P _{out}	Power Output	f = 1025 to 1150 MHz V _{cc} = 50Volts Pulse Width = 10 μsec Duty Cycle = 1%	150			Watts
P _{in}	Power Input				25	Watts
P _g	Power Gain		7.8			dB
η _c	Collector Efficiency			40		%
VSWR	Load Mismatch Tolerance				20:1	
B _{Vebo}	Breakdown Voltage (Emitter to Base)	I _c = 0A, I _e = 15mA	4.0			Volts
B _{Vces}	Breakdown Voltage (Collector to Emitter)	V _{be} = 0A, I _c = 25mA	55			Volts
h _{FE}	DC-Current Gain	V _{ce} = 5V, I _c = 250mA	20			
θ _{jc}	Thermal Resistance				0.6	°C/W

Note 1: T_c = +25°C unless otherwise specified

THERMAL RESISTANCE VS PULSE WIDTH

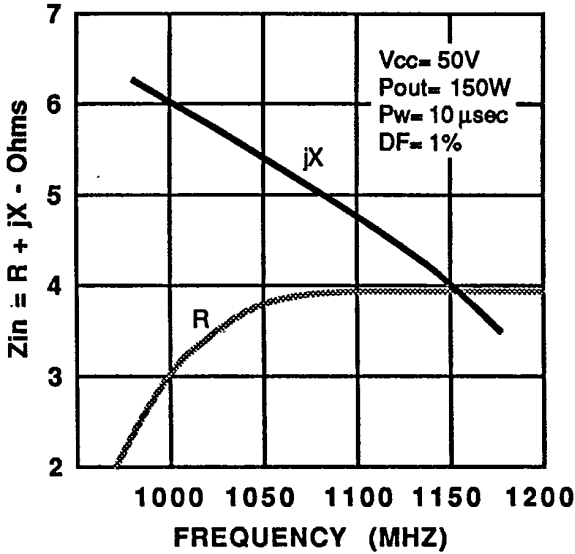


SPECIFICATIONS MAY BE SUBJECT TO CHANGE WITHOUT NOTICE

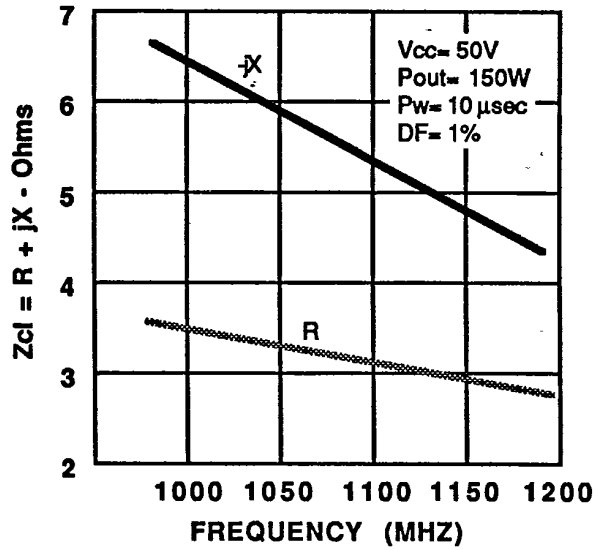
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DME 150-3

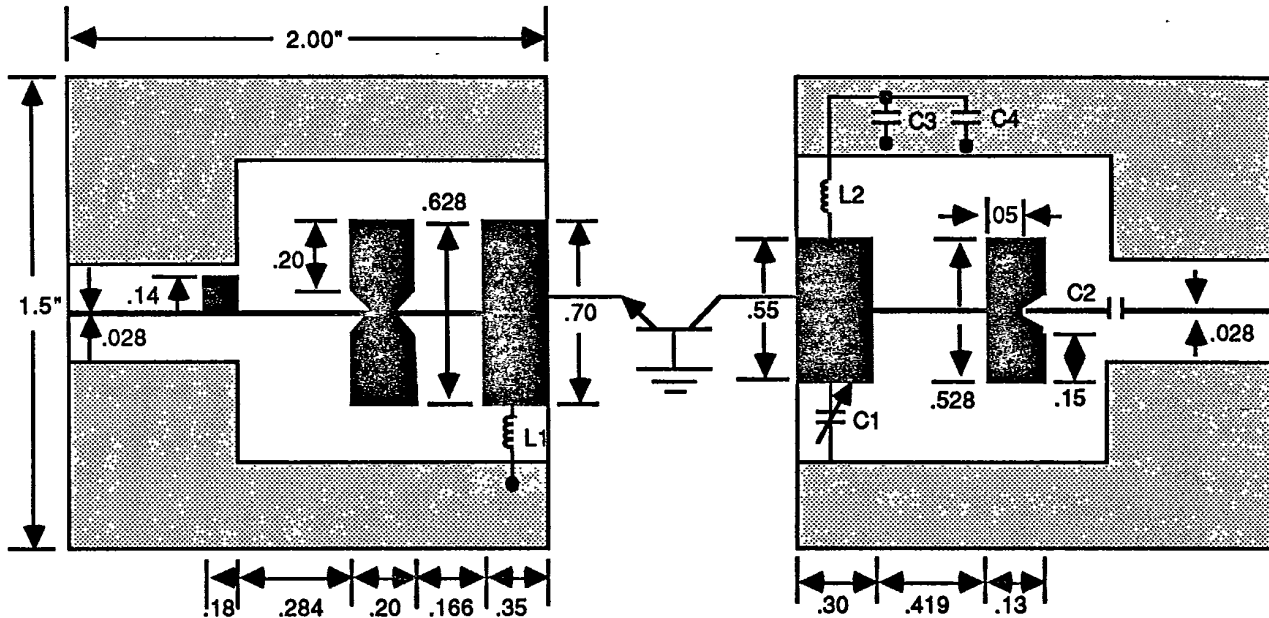
SERIES INPUT IMPEDANCE VS FREQUENCY (TYPICAL)



SERIES LOAD IMPEDANCE VS FREQUENCY (TYPICAL)



1025/1150 MHz TEST AMPLIFIER



Material = .010" Duroid

- L1= 1" No. 20 wire
- L2= 7 turns No. 20 wire, closewound 1/8" dia.
- C1= Johanson No. 5701, 6-6PF
- C2= A.T.C. Chip cap. 82PF
- C3= A.T.C. Chip cap. 92PF
- C4= 200μsec fD 50V

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